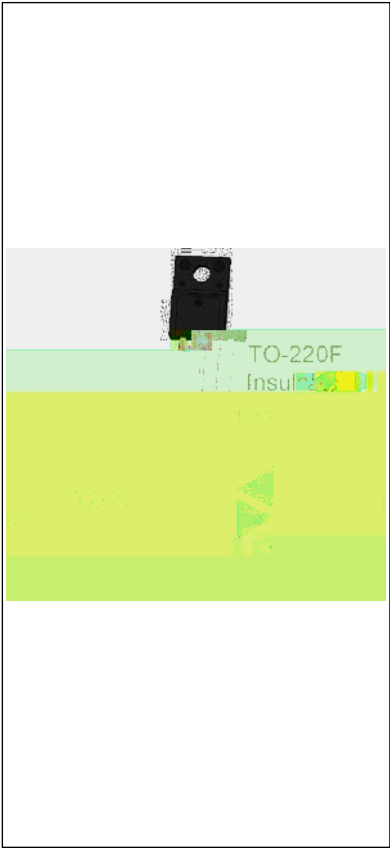




DESCRIPTION:



MAIN FEATURES

|  |  |  |
|--|--|--|
|  |  |  |
|  |  |  |
|  |  |  |
|  |  |  |

ABSOLUTE MAXIMUM RATINGS

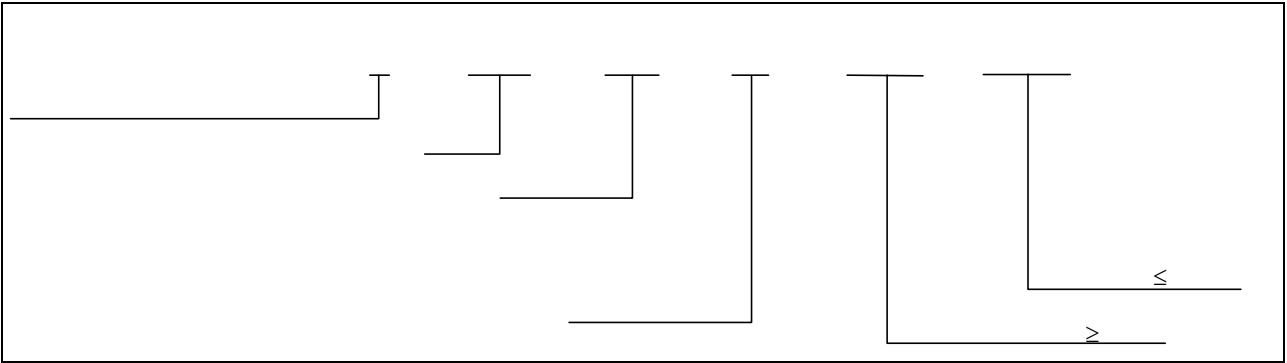
|   |  |  |  |
|---|--|--|--|
|   |  |  |  |
|   |  |  |  |
|   |  |  |  |
|   |  |  |  |
|   |  |  |  |
| ≤ |  |  |  |
|   |  |  |  |
|   |  |  |  |
|   |  |  |  |
| × |  |  |  |
|   |  |  |  |



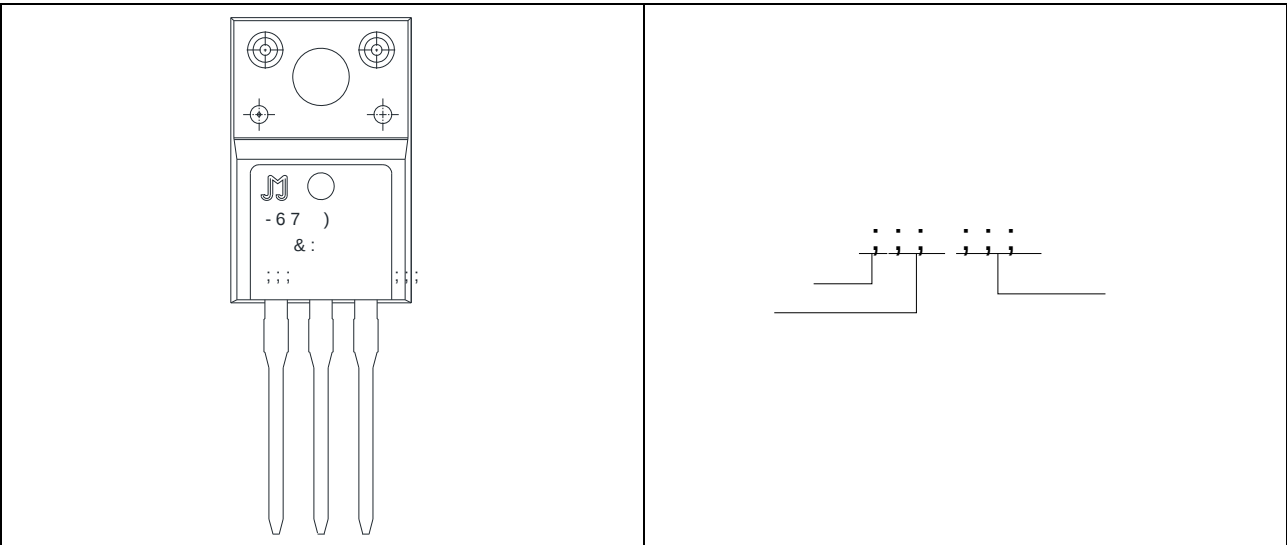
|  |  |  |  |
|--|--|--|--|
|  |  |  |  |
|  |  |  |  |



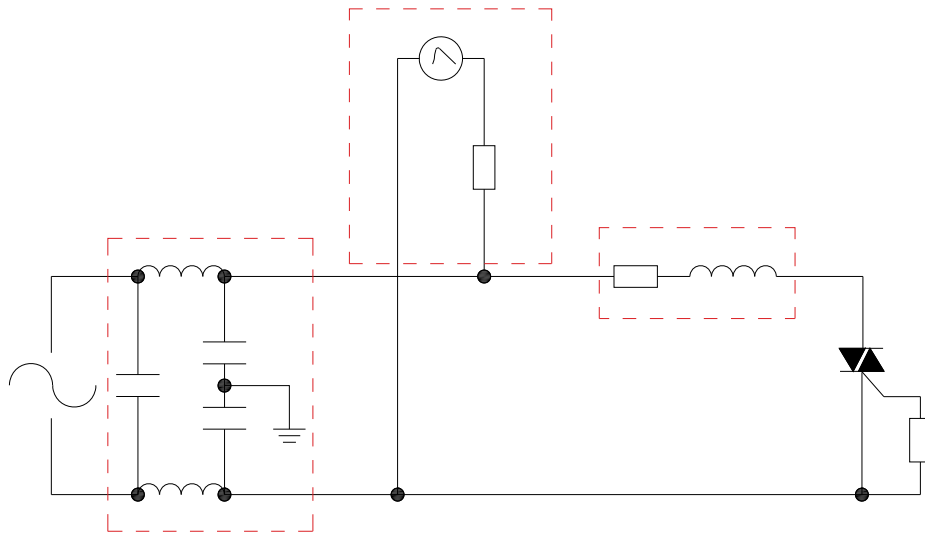
# ORDERING INFORMATION



# MARKING







## LEAD FORMING AND SOLDERING

Microelectronics.



ORDERING INFORMATION

|  |  |       |  |  |  |
|--|--|-------|--|--|--|
|  |  |       |  |  |  |
|  |  | H I J |  |  |  |
|  |  |       |  |  |  |

|  |  |  |
|--|--|--|
|  |  |  |
|  |  |  |
|  |  |  |



---

## PACKAGE MECHANICAL DATA



